

APPROVAL SHEET

MULTILAYER CERAMIC CAPACITORS

Ultra-small Series (6.3V to 50V)

01005 Size

NP0, X7R & X5R Dielectrics

Halogen Free & RoHS Compliance

*Contents in this sheet are subject to change without prior notice.

Approval Sheet

1. INTRODUCTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

01R5 MLCC is performed by high precision technology achieve high capacitance in unit size and ensure the stability and reliability of products.

2. FEATURES

- a. High capacitance in unit size.
- b. High precision dimensional tolerances.
- Suitable used in high-accuracy automatic mounting machine.

3. APPLICATIONS

- a. Miniature microwave module.
- b. Portable equipments (ex. Mobile phone, PDA).
- c. High frequency circuits.

4. HOW TO ORDER

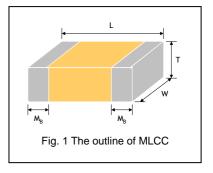
<u>01R5</u>	<u>N</u>	<u>100</u>	<u>C</u>	<u>160</u>	<u>C</u>	I
<u>Size</u>	Dielectric	<u>Capacitance</u>	<u>Tolerance</u>	Rated voltage	<u>Termination</u>	<u>Packaging</u>
		过度	PIT H	T St		
Inch (mm)	N =NP0	Two significant digits	A =±0.05pF	Two significant digits	C=Cu/Ni/Sn	T=7" reeled
01R5 =	(C0G)	followed by no. of zeros.	B =±0.1pF	followed by no. of		
01005 (0402)	B =X7R	And R is in place of	C =±0.25pF	zeros. And R is in		
	X =X5R	decimal point.	D =±0.5pF	place of decimal point.		
		##/	F=±1%	ען וונד		
		eg.:	G=±2%	6R3 =6.3 VDC		
		0R5=0.5pF PAS	J=±5%*YSTEM	100 =10 VDC		
		1R0=1.0pF	K =±10%	160 =16 VDC		
		100=10x10 ⁰	M =±20%	250 =25 VDC		
		=10pF		500 =50 VDC		
		MAISW	chnolog	Colo Series		



5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Syr	nbol	M _B (mm)
01R5 (0402)	0.40±0.02	0.20±0.02	0.20±0.02	V	0.10±0.03

^{*} Reflow soldering only.



6. GENERAL ELECTRICAL DATA

Size	01R5				
Dielectric	NP0	X7R	X5R		
Capacitance*	0.2pF to 100pF	100pF to 1000pF	1000pF to 0.1μF		
•	Cap≤5pF: A (±0.05pF), B (±0.1pF), C (±0.25pF) 5pF <cap<10pf: C (±0.25pF), D (±0.5pF) Cap≥10pF: F (±1%), G (±2%), J (±5%)</cap<10pf: 		,		
Rated voltage (WVDC)	16V, 25V, 50V	10V	6.3V, 10V		
DF / Q ^{#1}	Cap<30pF, Q≥400+20C Cap≥30pF, Q≥1000	≤5 %	≤10 %		
Insulation resistance at Ur	≥10GΩ or RxC≥500Ω*F	whichever is less	RxC≥50Ω*F		
Operating temperature	-55 to +125℃	-55 to +125℃	-55 to +85℃		
Capacitance change	±30ppm	±15°	%		
Termination	Ni/Sn (lead-free termination)				

^{*} Measured at 30~70% related humidity.

NP0: Apply 0.5~5Vrms, 1.0MHz±10% at the condition of 25°C ambient temperature.

X7R: Apply 1.0±0.2Vrms, 1.0kHz±10%, at 25°C ambient temperature.

X5R: Apply 0.5±0.2Vrms or 1.0±0.2Vrms

#1, 1.0kHz±10%, at the condition of 25°C ambient temp erature.

^{**} Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours before measurement.

^{#1:} Please refer to "RELIABILITY TEST CONDITIONS AND REQUIREMENTS" for detail

7. CAPACITANCE RANGE

	SIZE		01R5	
	DIELECTRIC	NP0		
RATED VOLTAGE (VDC)		16	25	50
	0.2pF (0R2)	V	V	V
	0.3pF (0R3)	V	V	V
	0.4pF (0R4)	V	V	V
	0.5pF (0R5)	V	V	V
	1.0pF (1R0)	V	V	V
	1.5pF (1R5)	V	V	V
	2.0pF (2R0)	V	V	V
	3.0pF (3R0)	V	V	V
	4.0pF (4R0)	V	V	V
	5.0pF (5R0)	V	V	V
	6.0pF (6R0)	V	V	V
ခ်	7.0pF (7R0)	V	V	V
tar	8.0pF (8R0)	V	V	V
aci	9.0pF (9R0)	V	V	V
Capacitance	10pF (100)	V	V	V
ပ	12pF (120)	V	V	V
	15pF (150)	V	V	V
	18pF (180)	V	V	V
	22pF (220)	V	V	V
	27pF (270)	V	V	V
	33pF (330)	V	V	V
	39pF (390)	V	V	VE
	47pF (470)		V	V
	56pF (560)	V	V	V
	68pF (680)		VXV	V
	82pF (820) 100pF (101)	V	V/7//	V

	SIZE	01R5
	DIELECTRIC	X7R
R.A	TED VOLTAGE (VDC)	10
	100pF (101)	V
Capacitance	150pF (151)	V
itaı	220pF (221)	V
oac	330pF (331)	V
Cal	470pF (471)	V
_	1,000pF (102)	V

	SIZE	01R5		
	DIELECTRIC	X5R		
RATED VOLTAGE (VDC)		6.3	10	
	1,000pF (102)	V	V	
	1,500pF (152)		V	
	2,200pF (222)		V	
	3,300pF (332)		V	
Capacitance	4,700pF (472)		V	
an	6,800pF (682)		V	
SCi	0.010µF (103)	V	V	
aps	0.015µF (153)			
ပိ	0.022µF (223)	V		
	0.033µF (333)	V		
	0.047µF (473)	V		
	0.068µF (683)			
	0.10µF (104)	V		

^{1.} The letter in cell is expressed the symbol of product thickness.

8. PACKAGING DIMENSION AND QUANTITY

Size	Thiskness (mm)/Sumbal		Paper tape	
Size Thickness (mm)/Symbol		OI	7" reel	13" reel
01R5 (0402)	0.20±0.02	V	20,000	-

Unit: pieces

^{2.} For more information about products with special capacitance or other data, please contact WTC local representative.



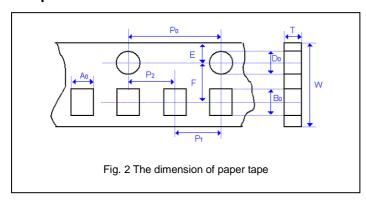
9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	Item	Test Condition	Requirements
1.	Visual and Mechanical		* No remarkable defect. * Dimensions to conform to individual specification sheet.
	Capacitance Q/ D.F. (Dissipation Factor)	Class I: NP0 Cap≤1000pF, 0.5~5Vrms, 1MHz±10% Cap>1000pF, 1.0±0.2Vrms, 1KHz±10% Class II: , X7R & X5R(≥10V) 1.0±0.2Vrms, 1KHz±10% Class II: , X5R(≤6.3V) 0.5±0.2Vrms, 1kHz±10% *Before initial measurement (Class II only): To apply de-aging at 150℃ for 1hr then set for 24±2 hrs at room temp.	* Shall not exceed the limits given in the detailed spec. * NP0: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C X7R: ≤5.0 % X5R: ≤10 %
4.	Dielectric Strength	* To apply voltage (≤100V) 250%. * Duration: 1 to 5 sec. * Charge and discharge current less than 50mA.	* No evidence of damage or flash over during test.
5.	Insulation Resistance	To apply rated voltage for max. 120 sec.	* NP0, X7R: ≥10GΩ or RxC≥500Ω-F whichever is smaller. X5R: RxC≥50Ω-F
6.	Temperature Coefficient	With no electrical load. T.C. Operating Temp NPO -55~125℃ at 25℃ X7R -55~125℃ at 25℃ *Before initial measurement (Class II only): To apply de-aging at 150℃ for 1hr then set for 24± 2 hrs at room temp. *Measurement voltage for Class II Cap≤0.01μF: 0.5V Cap>0.01μF: 0.2V	T.C. Capacitance Change NPO Within ±30ppm/°C X7R Within ±15% X5R Within ±15%
7.	Adhesive Strength of Termination	* Pressurizing force : 1N * Test time: 10±1 sec.	* No remarkable damage or removal of the terminations.
8.	Vibration Resistance	* Vibration frequency: 10-55 Hz/min. * Total amplitude: 1.5mm * Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.) * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Cap./DF(Q) Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	* No remarkable damage. * Cap change and Q/D.F.: To meet initial spec.
	Solderability Bending Test	* Solder temperature: 235±5°C * Dipping time: 2±0.5 sec. * The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm per second until the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec. * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Measurement to be made after keeping at room temp. for 24±2 hrs.	* No remarkable damage. * Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger. X7R: within ±12.5% X5R: within ±25.0% (This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test.)

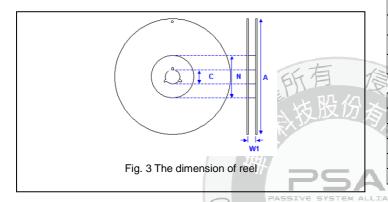
No.	Item	Test Condition	Requirements	
	Resistance to	* Solder temperature: 260±5°C * Dipping time: 10±1 sec	* No remarkable damage. * Cap change:	
		* Preheating: 120 to 150℃ for 1 minute before imme rse the capacitor in a eutectic solder. * Before initial measurement (Class II only): To apply de-aging at 150℃ for 1hr then set for 24±2 hrs at room temp. * Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150℃ for 1hr then set for 24±2 hrs at room temp.	NP0: within ±2.5% or ±0.25pF whichever is larger. X7R: within ±7.5% X5R: within ±15.0% Q/D.F., I.R. and dielectric strength: To meet initial requirements. * 25% max. leaching on each edge.	
12.	Temperature Cycle	* Conduct the five cycles according to the temperatures and time.	* No remarkable damage. * Cap change:	
	Cycle	Step Temp. (°C) Time (min.) 1 Min. operating temp. +0/-3 30±3 2 Room temp. 2-3 3 Max. operating temp. +3/-0 30±3 4 Room temp. 2-3 * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	NP0: within ±2.5% or ±0.25pF whichever is larger. X7R: within ±7.5% X5R: within ±15.0% * Q/D.F., I.R. and dielectric strength: To meet initial requirements.	
13.	Humidity (Steady State)	* Test temp.: 40±2°C * Humidity: 90~95% RH * Test time: 500+24/-0hrs. * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	X5R: within ±25.0%	
14.	Humidity Load (Damp Heat)	* Test temp.: 40±2°C * Humidity: 90~95%RH * Test time: 500+24/-0 hrs. * To apply voltage: rated voltage. * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	* No remarkable damage. * Cap change: NP0: within ±7.5% or ±0.75pF whichever is larger. X7R: within ±15.0% X5R: within ±25.0% * Q/D.F. value: NP0: Cap≥30pF, Q≥200; Cap<30pF; Q≥100+10/3C X7R: ≤7.5% X5R: ≤20% * I.R.: NP0, X7R: ≥500MΩ or RxC≥25Ω-F whichever is smaller. X5R: RxC≥5Ω-F.	
15.	High Temperature Load (Endurance)	* Test temp.: NP0, X7R: 125±3°C X5R: 85±3°C * To apply voltage: (1) NP0, X7R: 200% of rated voltage (2) X5R: 10V: 150 % of rated voltage 6.3V: 100 % of rated voltage * Test time: 1000+24/-0 hrs. * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. ** De-rating conditions:	* No remarkable damage. * Cap change: NP0: within ±3.0% or ±0.3pF whichever is larger. X7R: within ±12.5% X5R: within ±25.0%	

APPENDIXES

■ Tape & reel dimensions



Size	01R5
Thickness	V
A ₀	0.25 +/-0.05
B ₀	0.45 +/-0.05
Т	≦0.50
K ₀	-
w	8.00 +/-0.30
P ₀	4.00 +/-0.10
10xP ₀	40.00 +/-0.10
P ₁	2.00 +/-0.05
P ₂	2.00 +/-0.05
D ₀	1.50 +0.1/-0
D ₁	-
E	1.75 +/-0.10
F	3.50 +/-0.05



113/1	
Size	01R5
Reel size	7"
C	13.0+0.5/-0.2
$ W_1$	8.4+1.5/-0
- () A	178.0±1.0
N	60.0+1.0/-0

■ Example of customer label

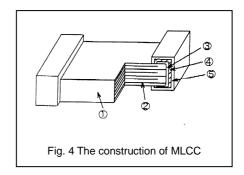


^{*}Customized label is available upon request

- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label

Constructions

No.	Name		NP0	X7R, X5R
①	Ceramic material		CaZrO₃ based	BaTiO₃ based
2	Inner electrode		Ni	
3		Inner layer	С	u
4	Termination	Middle layer	N	li
(5)		Outer layer	Sn (I	Matt)



Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N₂ within oven are recommended.

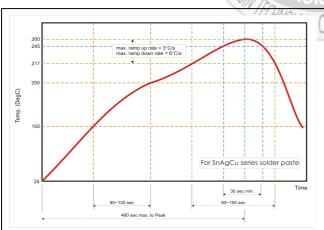


Fig. 5 Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.